

REMARKS

Claims 9 and 24 are now pending in the application. Claims 9 and 24 are now amended. The amendments are fully supported by the application as filed and do not present new subject matter. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

REJECTION UNDER 35 U.S.C. § 102/103

Claim 9 stands rejected under 35 U.S.C. § 102(b) as being anticipated by each of Gurtler et al. (U.S. Pat. No. 5,457,879) and Hedler (U.S. Pat. No. 6,555,415 B2). These rejections are respectfully traversed.

Claim 9 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over each of Hatakeyama Tomoyuki (JP No. 11-251363) and Kurashima Yohei (JP No. 2001-223243). These rejections are respectfully traversed.

Claim 24 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Gurtler et al. (U.S. Pat. No. 5,457,879) in view of Applicants' Prior Art Figures 10 and 11; Hedler (U.S. Pat. No. 6,555,415 B2) in view of Applicants' Prior Art Figures 10 and 11; Hatakeyama Tomoyuki (JP No. 11-251363) in view of Applicants' Prior Art Figures 10 and 11; and Kurashima Yohei (JP No. 2001-223243) in view of Applicants' Prior Art Figures 10 and 11. These rejections are respectfully traversed.

Amended Claims 9 and 24 each recite, with reference to Figure 6 for exemplary purposes only as the invention includes numerous embodiments. A first electrode pad 230a'' and a second electrode pad 230a''. The first and second electrode pads are mounted to a semiconductor device 230'' and covered by an electrode 231''. A

recessed portion 231d" is formed in a center portion of the electrode. The recessed portion is opposite to an interval between the first electrode pad and the second electrode pad.

The Gurtler et al. reference appears to disclose, with reference to Figure 1, an interconnect plug 22 operable to cooperate with interconnect receptacle 36. The interconnect plug appears mounted to pad 18 and the interconnect receptacle appears mounted to pad 32. The Gurtler et al. reference fails to disclose or suggest first and second electrode pads covered by an electrode, as well as a recessed portion in the electrode that is opposite to an interval between the first electrode pad and the second electrode pad, as set forth in amended Claims 9 and 24.

The Hedler reference appears to disclose, with reference to Figure 18, a flexible elevation 103 that cooperates with a flexible elevation 3. As set forth at Claim 1, it appears that the flexible elevation 3 is made of an insulating material, not a conductive electrode or wire. The Hedler reference fails to disclose or suggest first and second electrode pads mounted to a semiconductor device and covered by an electrode, as well as a recessed portion in the electrode opposite to an interval between the first electrode pad and the second electrode pad, as set forth in amended Claims 9 and 24.

The Tomoyuki reference appears to disclose, with reference to Figure 1, a semiconductor chip 1 having pads 2 and bumps 3. The bumps appear to cooperate with lands 4 of a wiring board 5. The Tomoyuki reference fails to disclose or suggest first and second electrode pads mounted to a semiconductor device and covered by an electrode, as well as a recessed portion formed in the electrode that is opposite to an

interval between the first electrode pad and the second electrode pad, set forth in amended Claims 9 and 24.

The Yohei reference appears to disclose, with reference to Figure 1, a semiconductor chip 10 having an electrode 12 and a bump 16. The bump 16 appears to cooperate with a joint 24 and a wiring 22 of a board 20. The Yohei reference fails to disclose or suggest first and second electrode pads mounted to a semiconductor device and covered by an electrode, as well as a recessed portion formed in the electrode opposite to an interval between the first electrode pad and the second electrode pad, as set forth in amended Claims 9 and 24.

Applicants Prior Art Figures 10 and 11 appear to disclose a semiconductor device 130 having a device electrode 131 and a wiring substrate 120 having a wiring terminal 121. The Prior Art Figures fail to disclose or suggest first and second electrode pads mounted to a semiconductor device and covered by an electrode, as well as a recessed portion formed in the electrode opposite to an interval between the first electrode pad and the second electrode pad, as set forth in amended Claims 9 and 24.

As set forth above the Gurtler et al., Hedler, Tomoyuki, and Yohei references and Applicants' Prior Art Figures 10 and 11, each fail to disclose or suggest each and every feature of amended Claims 9 and 24. For example, the cited references and figures fail to disclose or suggest first and second electrode pads mounted to a semiconductor device and covered by an electrode, as well as a recessed portion formed in the electrode opposite to an interval between the first electrode pad and the second electrode pad, as set forth in amended Claims 9 and 24. Therefore, combination of the cited references and figures fails to disclose or suggest these features of amended


Claims 9 and 24. Applicants respectfully request reconsideration and withdrawal of these Section 102 and 103 rejections.

CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicants therefore respectfully request that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action and the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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